

Comparison of the TMS320C55x DSP EMIF and the TMS320C6000 DSP EMIF

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TMS320C5000 Hardware Applications

ABSTRACT

This document compares the features of the TMS320C55x™ DSP external memory interface (EMIF) and the TMS320C6000™ DSP EMIF. Both interfaces support asynchronous memory, synchronous burst static random access memory (SBSRAM), and synchronous dynamic random access memory (SDRAM).

This application note is not a complete reference of the features of these EMIFs. For full details, see *TMS320C55x DSP Peripherals Reference Guide* (SPRU317) and *TMS320C6000 Peripherals Reference Guide* (SPRU190).

Overview

The TMS320C55x™ DSP and the TMS320C6000™ DSP have similar external memory interfaces (EMIFs). Both EMIFs provide support for synchronous dynamic random access memory (SDRAM), synchronous burst static random access memory (SBSRAM), and asynchronous memories (ROM, RAM, and flash). This application report lists the EMIF differences in the following C55x™ DSPs and C6000™ DSPs:

- TMS320VC5510 DSP
- TMS320C6201 DSP
- TMS320C6202 DSP
- TMS320C6211 DSP
- TMS320C6701 DSP
- TMS320C6711 DSP

C55x™ DSP and C6000™ DSP EMIF Differences

Table 1 provides a cross reference of the EMIF features supported on the DSPs. The table provides separate sections for clock, SDRAM, SBSRAM, asynchronous, and miscellaneous features. S, W, and P in the miscellaneous section are synchronous, write performance, and power savings.

Table 1. EMIF Features Supported on C55x DSPs and C6000 DSPs

| C55x DSP or C6000 DSP Device | EMIF Features | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
|------------------------------|---------------|----|----|----|-------|----|----|----|----|----|----|----|----|----|----|----|--------|----|----|----|----|----|---------|----|----|----|----|-------|----|----|----|---|
| | Clock | | | | SDRAM | | | | | | | | | | | | SBSRAM | | | | | | Asynch. | | | | | Misc. | | | | |
| | C1 | C2 | C3 | C4 | D1 | D2 | D3 | D4 | D5 | D6 | D7 | D8 | D9 | DA | DB | DC | DD | B1 | B2 | B3 | B4 | B5 | B6 | A1 | A2 | A3 | A4 | A5 | S1 | W1 | P1 | |
| VC5510 | X | X | X | | | X | X | | X | X | | | X | | X | X | X | | | | X | X | | X | X | X | X | X | X | X | X | X |
| C6201/C6701 | X | X | X | X | | | X | X | X | | | | X | | X | X | X | | | | X | X | | X | X | X | X | X | X | X | | X |
| C6202 | | X | X | | | | X | X | X | | | | X | | X | X | X | | | | X | X | | X | X | X | X | X | X | | | X |
| C6211/C6711 | X | X | | | X | X | X | X | X | X | X | X | X | X | X | X | X | X | X | X | X | X | X | X | X | X | X | X | X | | | X |

Table 2 describes the EMIF features on C55x DSPs and C6000 DSPs. The order of the feature sections in Table 2 matches the order of features provided in Table 1.

Table 2. Description of EMIF Features on C55x DSPs and C6000 DSPs

| Feature | Description | Supported on Devices | | |
|---------------|---|--|-----------|--|
| | | C55x DSP | C6000 DSP | |
| Clocks | | | | |
| C1 | Synchronous memory clock at 1X DSP | SDRAM/SBSRAM clock at a DSP CPU clock frequency multiple of 1X | VC5510 | 6201(SBSRAM) 6701(SBSRAM) 6211(external) 6711(external) |
| C2 | Synchronous memory clock at 1/2X DSP | SDRAM/SBSRAM clock at a DSP CPU clock frequency multiple of 1/2X | VC5510 | 6201, 6701, 6202, 6211(external), 6711(external) |
| C3 | Synchronous memory clock output disable | Enable/disable of synchronous memory clock output | VC5510 | 6201, 6701, 6202 |
| C4 | Separate clocks for SBS/SDRAM | SBSRAM and SDRAM have separate synchronous memory clock outputs. | None | 6201, 6701 |
| SDRAM | | | | |
| D1 | 256-Mbit SDRAM | SDRAM 256M-bit memory size supported | None | 6211, 6711 |
| D2 | 128-Mbit SDRAM | SDRAM 128M-bit memory size supported | VC5510 | 6211, 6711 |
| D3 | 64-Mbit SDRAM | SDRAM 64M-bit memory size supported | VC5510 | All |
| D4 | 16-Mbit SDRAM | SDRAM 16M-bit memory size supported | None | All |
| D5 | 32-bit SDRAM | SDRAM data bus interface width of 32 bits | VC5510 | All |
| D6 | 16-bit SDRAM | SDRAM data bus interface width of 16 bits | VC5510 | 6211, 6711 |
| D7 | 8-bit SDRAM | SDRAM data bus interface width of 8 bits | None | 6211, 6711 |
| D8 | SDRAM CAS latency 2 | SDRAM read latency of 2 memory clock cycles | None | 6211, 6711 |
| D9 | SDRAM CAS latency 3 | SDRAM read latency of 3 memory clock cycles | VC5510 | All |
| DA | SDRAM serial burst length 4 | SDRAM serial (sequential) burst length of 4 locations | None | 6211, 6711 |

Table 2. Description of EMIF Features on C55x DSPs and C6000 DSPs (Continued)

| Feature | | Description | Supported on Devices | |
|--------------------------|-----------------------------------|---|-------------------------|---|
| | | | C55XX | 6XXX |
| SDRAM (Continued) | | | | |
| DB | SDRAM serial burst length 1 | SDRAM serial (sequential) burst length of 1 location | VC5510 | All |
| DC | SDRAM multiple pages open | Multiple SDRAM pages simultaneously open | None | 6211, 6711 |
| DD | SDRAM timing configuration | SDRAM timing parameters programmability | VC5510 | All |
| SBSRAM | | | | |
| B1 | 32-bit SBSRAM | Non-parity SBSRAM data bus width of 32 bits | VC5510 | All |
| B2 | 16-bit SBSRAM | Non-parity SBSRAM data bus width of 16 bits | None | 6211, 6711 |
| B3 | 8-bit SBSRAM | Non-parity SBSRAM data bus width of 8 bits | None | 6211, 6711 |
| B4 | SBSRAM P, SCD | Pipeline, single cycle deselect SBSRAM support | VC5510 | All |
| B5 | SBSRAM linear burst | SBSRAM linear burst mode support | VC5510 | All |
| B6 | SBSRAM/ADV | SBSRAM /ADV internal burst advance support | None | 6211, 6711 |
| Asynchronous | | | | |
| A1 | 32-bit asynchronous | Asynchronous memory 32-bit data bus width supported | VC5510 | All |
| A2 | 16-bit asynchronous | Asynchronous memory 16-bit data bus width supported | VC5510 | 6201(ROM), 6701(ROM), 6202(ROM), 6211, 6711 |
| A3 | 8-bit asynchronous | Asynchronous memory 8-bit data bus width supported | VC5510(ROM) | 6201(ROM), 6701(ROM), 6202(ROM), 6211, 6711 |
| A4 | Asynchronous ready | Asynchronous memory ready input used to insert wait states for slow memories | VC5510 | All |
| A5 | Asynchronous timing configuration | Asynchronous memory read/write: strobe, setup, and hold width programmability | VC5510 | All |
| Synchronous | | | | |
| S1 | Both SDRAM and SBSRAM | Both SDRAM and SBSRAM possible in same system | VC5510 | 6201, 6701 |
| Write Performance | | | | |
| W1 | Write posting | Write posting support for improved write performance | VC5510 | None |
| Power Savings | | | | |
| P1 | Power down | Power down of internal EMIF clock | VC5510 (idle domain) | All |

References

1. *TMS320C55x DSP Peripherals Reference Guide (SPRU317)*
2. *TMS320C6000 Peripherals Reference Guide (SPRU190)*

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